C8728

Conductor

Description

C8728 is a Ag conductor paste that yields a smooth, dense film on alumina. This material is recommended for general purposes and for large ground plane areas. C8728 provides excellent solderability, void free soldering and good solder leach resistance.

Key Features

- Excellent fired film density High aged adhesion Excellent solderability with Sn62 and Sn95/Ag5

This picture does not show the packaging of C8728 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Conductivity	≤ 3.0 milliohms/square at 12 um fired film thickness
Viscosity	90 – 150 Kcps Brookfield HBTSC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide	
Process Temperature (TDS)	850 °C peak temperature Dwell time of 10 – 12 minutes,Total cycle time 36 – 60 minutes
Film Thickness	10 – 15 µm

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All changes are based on information displayed using the template data_sheet/HET/TFM/print_data_sheet.html.twig.
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